



boschman
advanced packaging technology

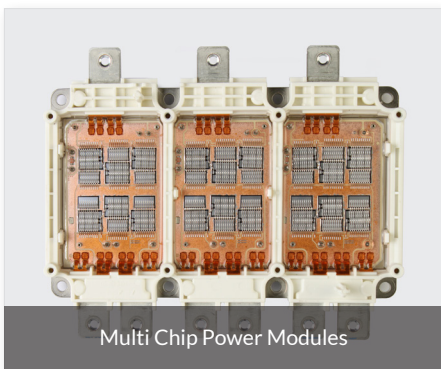
PACKAGE DEVELOPMENT AND PROTOTYPING

For power electronics in electrical vehicles

Package development and prototyping for power electronics in electrical vehicles

Boschman is a high-tech company focusing on advanced packaging solutions for power electronics. We provide a unique one-stop-shop concept – from idea to industrialization – offering our customers one point of contact for all packaging activities for next-gen power modules, starting from conceptual design to high volume production, enabling our customers with the highest power density and reliability available in the industry, combined with the lowest cost-of-ownership and time-to-market. Our leading technology in Silver Sintering and Film Assisted Molding is supported by our core Dynamic Insert Technology and deep in-house application knowledge.

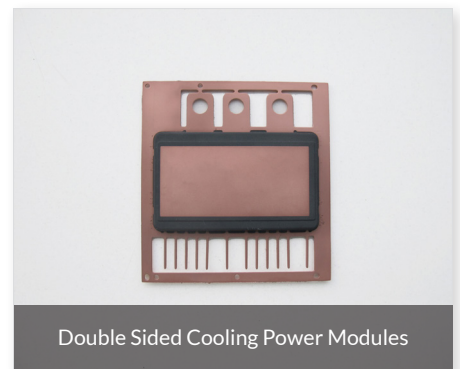
PACKAGING INTEGRATION TRENDS



Multi Chip Power Modules



Modular Power Discretes



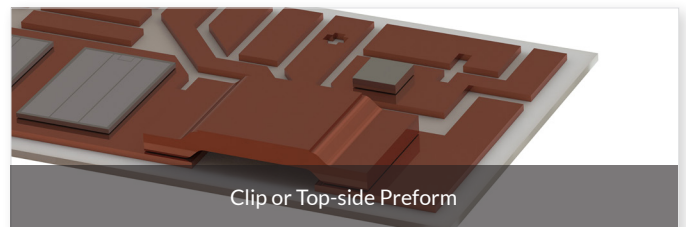
Double Sided Cooling Power Modules

* Infineon Technology – Hybridpack drive – Courtesy of System Plus Consulting 2019

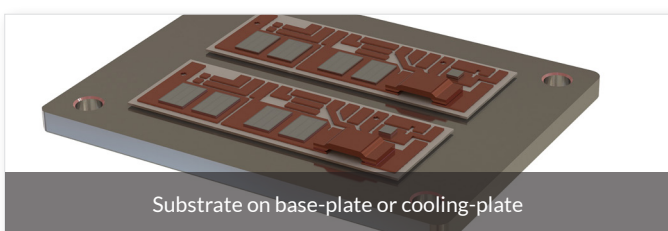
NEXT GEN SINTER SOLUTIONS



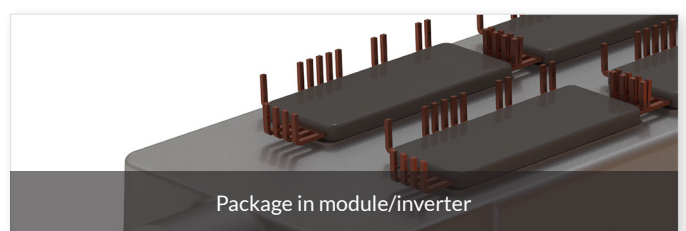
Sinter Die Attach



Clip or Top-side Preform

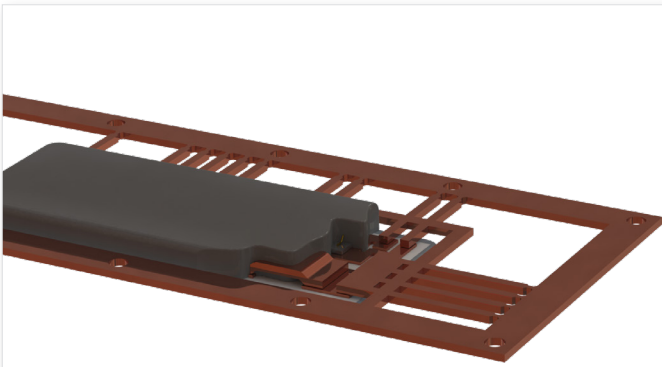


Substrate on base-plate or cooling-plate

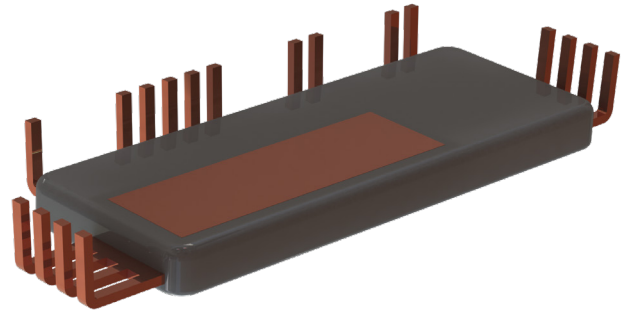


Package in module/inverter

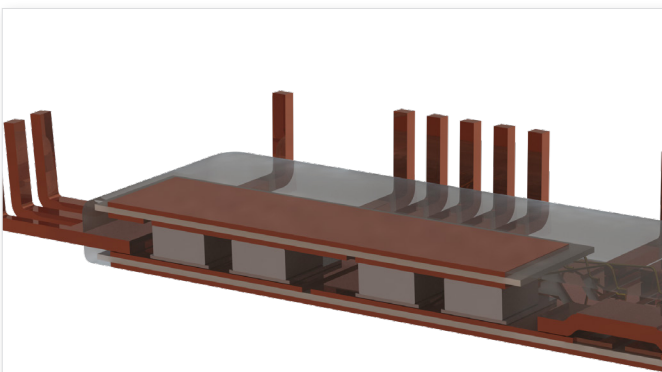
NEXT GEN MOLDING SOLUTIONS



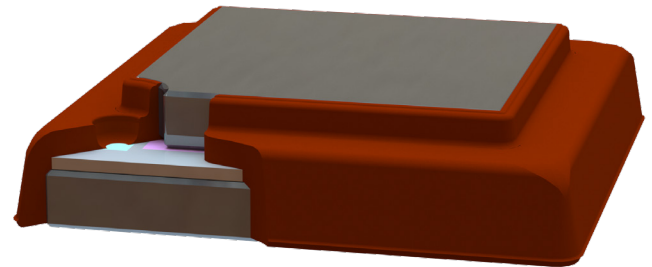
Integrated package design for sintering, molding and module integration with short time-to-market.



Film-Assisted-Molding (FAM) enables fully exposed double-sided cooling areas.



Critical stack-ups of tolerances are compensated in the molding process using our proprietary Dynamic Insert Technology (DIT).



Small high-density design solutions in a variety of form-factors providing maximum flexibility.

ONE-STOP-SHOP FROM IDEA TO INDUSTRIALIZATION



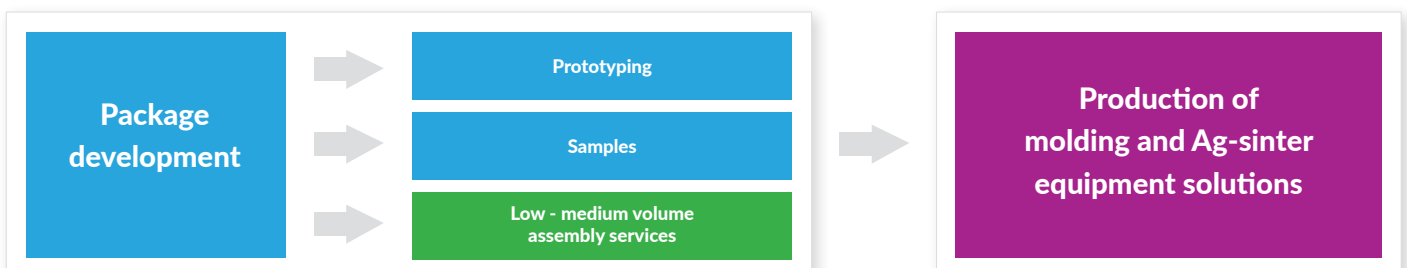
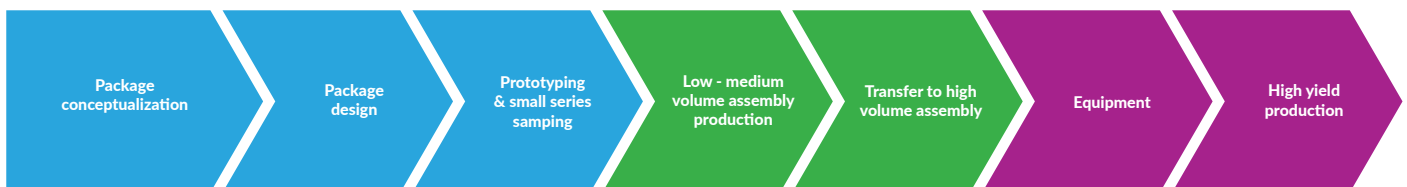
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development**
by boschman



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“ SMALLER, BETTER AND LOWER
COST, WE REALIZE THE BEST
PACKAGE FOR YOUR PRODUCT “



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Stenograaf 3 6921 EX Duiven T +31 26 319 4900 E info@boschman.nl

www.boschman.nl